**ON Semiconductor** 

Is Now

# Onsemi

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# **MOSFET** - N-Channel Shielded Gate PowerTrench<sup>®</sup>

150 V, 7.9 mΩ, 95.6 A

# NTMFS7D5N15MC

#### Features

- Small Footprint (5 x 6 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low QG and Capacitance to Minimize Driver Losses
- 100% UIL Tested
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **Typical Applications**

- Synchronous Rectification
- AC-DC and DC-DC Power Supplies
- AC-DC Adapters (USB PD) SR
- Load Switch

#### **MAXIMUM RATINGS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise noted)

Parameter		Symbol	Value	Unit	
Drain-to-Source Voltage		V <sub>DSS</sub>	150	V	
Gate-to-Source Voltage		V <sub>GS</sub>	±20	V	
Continuous Drain Current $R_{\theta JC}$ (Note 2)	Steady State	′ T <sub>C</sub> = 25°C	۱ <sub>D</sub>	95.6	A
Power Dissipation $R_{\theta JC}$ (Note 2)			P <sub>D</sub>	166.7	W
Continuous Drain Current R <sub>θJA</sub> (Notes 1, 2)	Steady State		Ι <sub>D</sub>	13.5	A
Power Dissipation $R_{\theta JA}$ (Notes 1, 2)			P <sub>D</sub>	3.3	W
Pulsed Drain Current	T <sub>C</sub> = 25°	C, t <sub>p</sub> = 100 μs	I <sub>DM</sub>	478	А
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	−55 to +175	°C
Single Pulse Drain-to-Source Avalanche Energy ( $I_L = 18 A_{pk}, L = 3 mH$ )			E <sub>AS</sub>	486	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface-mounted on FR4 board using a 1 in<sup>2</sup>, 2 oz. Cu pad.

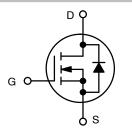
The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.



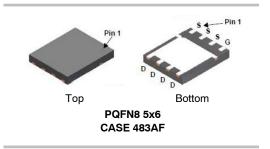
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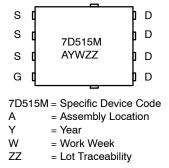
V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
150 V	7.9 mΩ @ 10 V	95.6 A



N-CHANNEL MOSFET







#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NTMFS7D5N15MC	Power 56	3000 / Tape
(Pb-Free/Halogen Free)	(PQFN8)	& Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 2)	$R_{ extsf{ heta}JC}$	0.9	°C/W
Junction-to-Ambient - Steady State (Notes 1, 2)	$R_{ hetaJA}$	45	

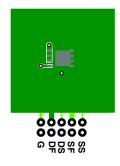
#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
OFF CHARACTERISTICS	-		•	-	-	-
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, I <sub>D</sub> = 250 $\mu$ A	150			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> / T <sub>J</sub>	$I_D = 250 \ \mu A$ , ref to $25^{\circ}C$		83		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V,$ $V_{DS} = 120 V$ $T_{J} = 25^{\circ}C$			1.0	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = ±20 V			±100	nA
ON CHARACTERISTICS					-	
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS}$ = $V_{DS}$ , $I_D$ = 295 $\mu$ A	2.5		4.5	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>	$I_D = 295 \ \mu\text{A}$ , ref to $25^{\circ}\text{C}$		-8.3		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 54 A		6.4	7.9	mΩ
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 8 V, I <sub>D</sub> = 27 A		6.9	9.2	mΩ
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 54 A		91		S
CHARGES, CAPACITANCES & GATE RESIS	TANCE					
Input Capacitance	C <sub>ISS</sub>			3835		
Output Capacitance	C <sub>OSS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 75 V		1070		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			11		
Gate-Resistance	R <sub>G</sub>			0.6	1.2	Ω
Total Gate Charge	Q <sub>G(TOT)</sub>			46		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>			12		
Gate-to-Source Charge	Q <sub>GS</sub>	$V_{GS}$ = 10 V, $V_{DS}$ = 75 V; $I_{D}$ = 54 A		20		
Gate-to-Drain Charge	Q <sub>GD</sub>			7		
Plateau Voltage	V <sub>GP</sub>			6		V
Output Charge	Q <sub>OSS</sub>	$V_{DD}$ = 75 V, $V_{GS}$ = 0 V		116		nC
SWITCHING CHARACTERISTICS					-	
Turn-On Delay Time	t <sub>d(ON)</sub>			27		ns
Rise Time	t <sub>r</sub>	V <sub>GS</sub> = 10 V, V <sub>DD</sub> = 75 V,		6		
Turn-Off Delay Time	t <sub>d(OFF)</sub>	$I_D = 54 \text{ A}, \text{ R}_G = 6 \Omega$		32		
Fall Time	t <sub>f</sub>			5		
DRAIN-SOURCE DIODE CHARACTERISTIC	s					
Forward Diode Voltage	V <sub>SD</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{S} = 54 \text{ A}$ $T_{J} = 25^{\circ}\text{C}$		0.87	1.2	V
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, V <sub>DD</sub> = 75 V		59		ns
Reverse Recovery Charge	Q <sub>RR</sub>	$dI_{S}/dt = 100 \text{ A}/\mu \text{s}, I_{S} = 54 \text{ A}$		111		nC
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, V <sub>DD</sub> = 75 V		44		ns
Reverse Recovery Charge	Q <sub>RR</sub>	$dI_S/dt = 1000 \text{ A}/\mu \text{s}, I_S = 54 \text{ A}$		616		nC

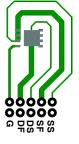
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NOTES:

3.  $R_{\theta JA}$  is determined with the device mounted on a 1 in<sup>2</sup> pad 2 oz copper pad on a 1.5 × 1.5 in. board of FR-4 material.  $R_{\theta CA}$  is determined by the user's board design.

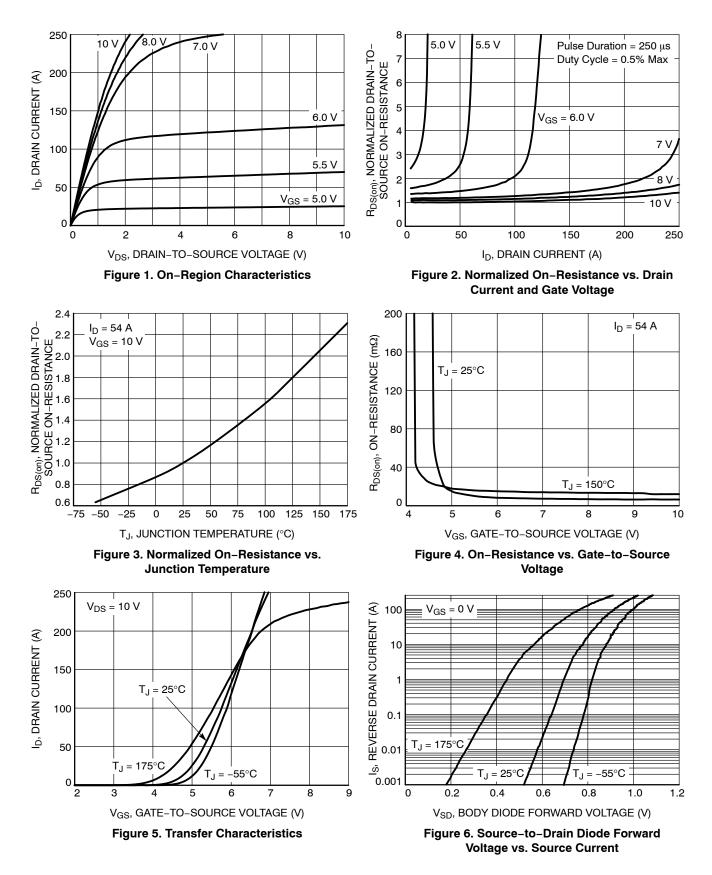


a) 45°C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper.

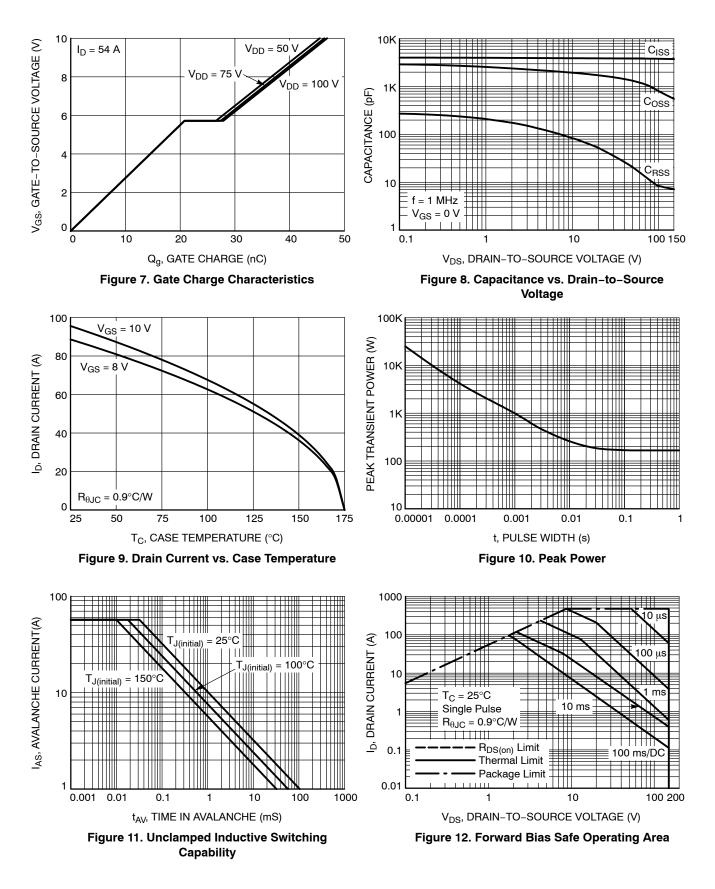


b) 115°C/W when mounted on a minimum pad of 2 oz copper.

#### **TYPICAL CHARACTERISTICS**



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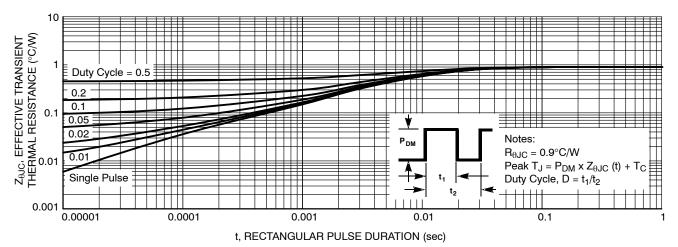
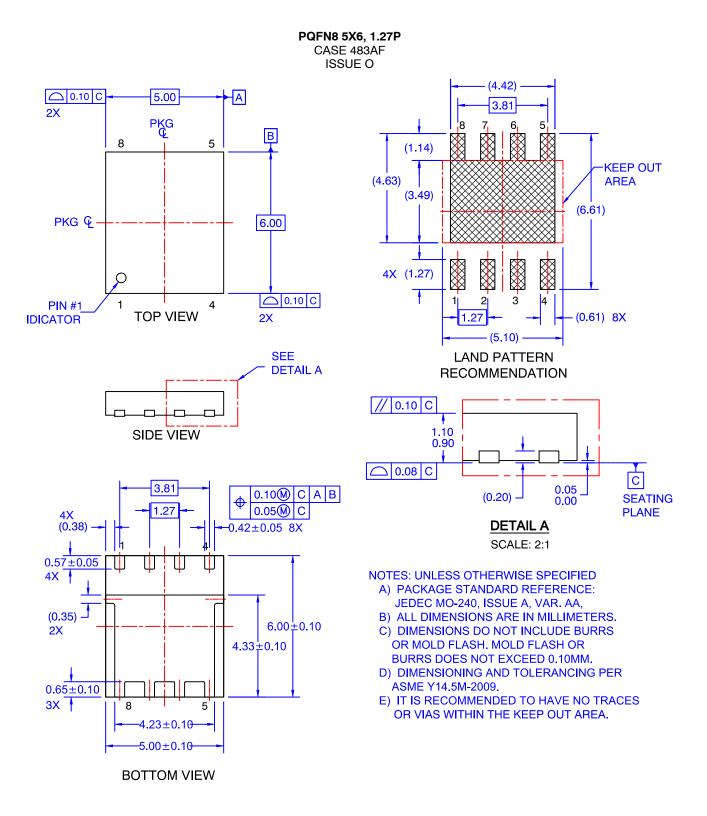


Figure 13. Transient Thermal Impedance

#### PACKAGE DIMENSIONS



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